

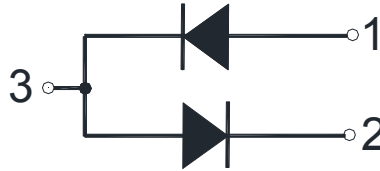
TD10F2-HAF

Surface Mount Fast Recovery Bridge Rectifier

Reverse Voltage - 1000 V
Forward Current - 1 A

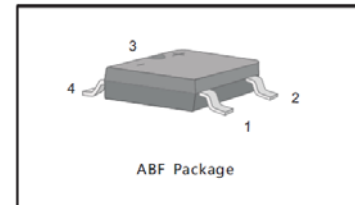
Features

- Glass Passivated Chip Junction
- High Surge Current Capability
- Halogen and Antimony Free(HAF),
RoHS compliant



PINNING

PIN	DESCRIPTION
1	Input Pin (-)
2	Input Pin (-)
3	Output Pin
4	N.C.



Mechanical Data

- Package: ABF
- Terminals: Solderable per MIL-STD-750, Method 2026

Maximum Ratings and Electrical characteristics

Single-phase, half-wave, 60 Hz, resistive or inductive load rating at 25°C, unless otherwise specified, for capacitive load, derate current by 20 %.

Parameter	Symbols	TD10F2	Units
	Marking	10F2	-
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	1000	V
Maximum RMS voltage	V_{RMS}	700	V
Maximum DC Blocking Voltage	V_{DC}	1000	V
Average Forward Current $T_a = 50^\circ\text{C}$	$I_{F(AV)}$	1	A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load	I_{FSM}	35	A
Maximum Instantaneous Forward Voltage at 1 A	V_F	1.1	V
Maximum DC Reverse Current at Rated DC Blocking Voltage $T_a = 25^\circ\text{C}$ $T_a = 125^\circ\text{C}$	I_R	1 50	μA
Typical Junction Capacitance ¹⁾	C_j	30	pF
Maximum Reverse Recovery Time ²⁾	t_{rr}	500	ns
Operating and Storage Temperature Range	T_j, T_{stg}	- 55 to + 150	$^\circ\text{C}$

¹⁾ Measured at 1 MHz and applied reverse voltage of 4 V D.C.

²⁾ Measured with $I_F = 0.5\text{ A}$, $I_R = 1\text{ A}$, $I_{rr} = 0.25\text{ A}$.

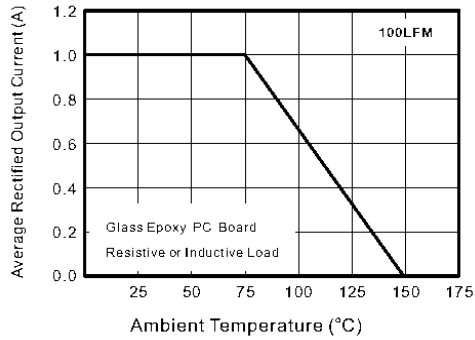
TOP DYNAMIC



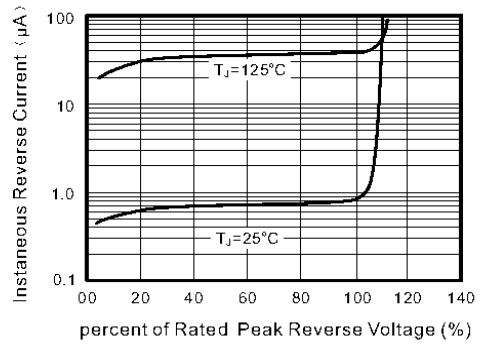
ISO14001 : 2004 Certificate No. 121509007
ISO 9001 : 2008 Certificate No. 50114012
OHSAS 18001 : 2007 Certificate No. 0513150006
IECQ QC 080000 Certificate No. E0241000741002

Dated: 12/09/2016 Rev: 01

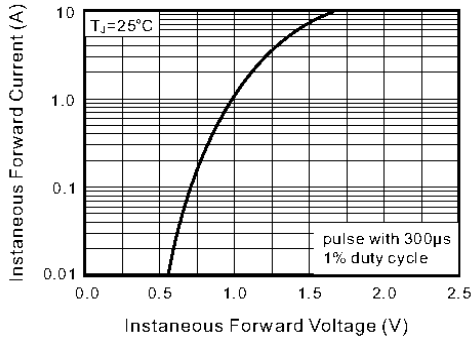
Average Rectified Output Current Derating Curve



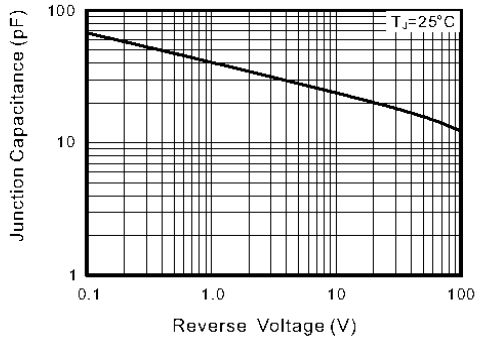
Typical Reverse Characteristics



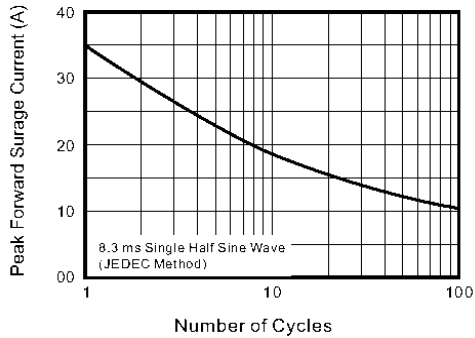
Typical Instantaneous Forward Characteristics



Typical Junction Capacitance



Maximum Non-Repetitive Peak Forward Surge Current

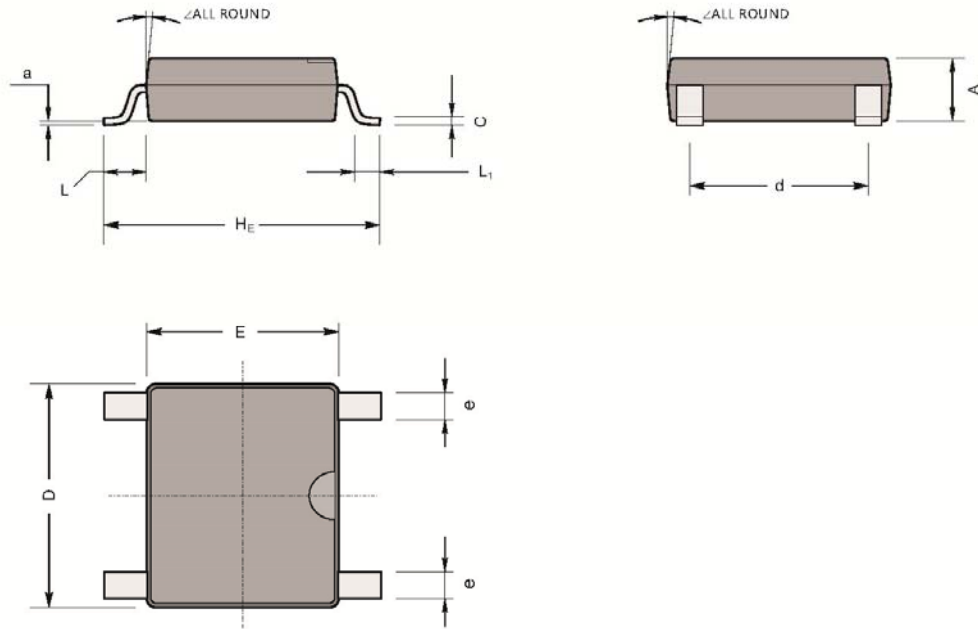


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PACKAGE OUTLINE

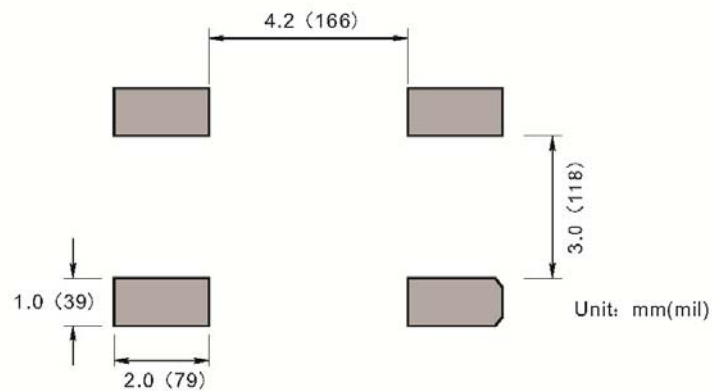
ABF

Plastic surface mounted package; 4 leads



UNIT	A	C	D	E	H_E	d	e	L	L1	a	\sphericalangle
mm	1.2	0.22	5.2	4.5	6.4	4.2	0.7	0.95	0.6	0.1	7°
	1	0.15	4.9	4.2	6	3.6	0.5				

Recommended Soldering Footprint



TOP DYNAMIC